600584

Jiangsu Changjiang Electronics Technology Co., Ltd.

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QFII

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120,000

9.5 FC	84,080	84,080
	--	35,920
	--	**120,000**

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/ /		2013 234,962,406 A
		A
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		Integrated Circuit, IC
		IC IC
FC/		Flip Chip
BGA		Ball Grid Array
FCBGA		Flip Chip Ball Grid Array
Flip Chip on L/F		Flip Chip on Lead/Fram

FCLGA		Flip Chip Land Grid Array
Bumping		FC UBM Cr Ni Ti Ti/w Cu Au
MEMS		Micro Electro Mechanical systems
Yole Développement		
WLCSP		Wafer Level Chip Scale Packaging CSP
TSV		Through-Silicon Via
SiP		System in Package

Jiangsu Changjiang Electronics Technology Co.,Ltd.

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85,313.361

600584

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2011 “ ”

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2012

FC FC

QFII

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9.5 FC	84,080	84,080
	--	35,920
	--	**120,000**

853,133,610

138,927,411 16.28%

234,962,406

234,962,406

1,088,096,016

12.77%

2013 11 27

LED

2005 3,800 2012 8,558.6 2012

59.26%

2005 985.78 2012 2,158.45

AP

2 FC

2008

2010

2006 511.6 2012

1,035.67

I/O

FC I/O

FC

FC FC

Yole Développement 2012 FC 200

2018 350 28nm IC DDR

2.5D/3D IC interposer FC

FC

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2011 “

0.8 BGA

PGA CSP MCM

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FC BGA CSP MCP

SiP 3D

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2012 28 “

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2012

546 68 471

TSV SiP

Cu Pillar Bumping FCBGA 50 m MEMS

FC

FC

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Bumping 8″ 12″ WLCSP 3P3M BGA

12″40nm low-k BGA

FC Flip Chip on L/F FCLGA FCBGA

Bumping Flip Chip

Fl2DTcl1943C3>19S

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116,700

12,828

2010 2011 2012 2013 9
46.47% 57.50% 62.98% 65.58%

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2010 2011 2012
2013 1-9 9,032.43 10,015.91
15,725.51 13,486.27

853,133,610

138,927,411

“ 9.5 FC ”

16.28%

5%

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2010 2012

2012	0.00	1,041.00	-
2011	0.00	6,731.71	-
2010	5,118.80	20,771.21	24.64%
			9,514.64
			53.80%

30%

2011 2012

2011

2012

2013 ~2015

2013 -2015

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